

David C Whalley

List of Publications by Year in descending order

Source: <https://exaly.com/author-pdf/3751167/publications.pdf>

Version: 2024-02-01

24
papers

143
citations

1937685

4
h-index

1720034

7
g-index

25
all docs

25
docs citations

25
times ranked

119
citing authors

#	ARTICLE	IF	CITATIONS
1	Direct-write techniques for maskless production of microelectronics: A review of current state-of-the-art technologies. , 2009, , .		50
2	Mechanical characterization of individual Ni•Au coated microsize polymer particles. Applied Physics Letters, 2008, 92, .	3.3	13
3	Damp•heat induced degradation in photovoltaic modules manufactured with passivated emitter and rear contact solar cells. Progress in Photovoltaics: Research and Applications, 2022, 30, 1061-1071.	8.1	12
4	Mechanical Performance of Polymer Cored BGA Interconnects. , 2008, , .		9
5	A review of LED technology trends and relevant thermal management strategies. , 2014, , .		9
6	Metal-coated mono-sized polymer core particles for fine pitch flip-chip interconnects. , 2012, , .		8
7	Interfacial Reaction Between Molten Sn-Bi Based Solders and Electroless Ni-P Coatings for Liquid Solder Interconnects. IEEE Transactions on Components and Packaging Technologies, 2008, 31, 574-585.	1.3	5
8	Magnetic deposition of Ni/Au coated polymer core particles for flip-chip interconnection. , 2014, , .		5
9	Relative Contributions of Packaging Elements to the Thermal Hysteresis of a MEMS Pressure Sensor. Sensors, 2020, 20, 1727.	3.8	5
10	IGBT Package Design for High Power Aircraft Electronic Systems. Journal of Electronic Packaging, Transactions of the ASME, 2001, 123, 338-343.	1.8	4
11	Current leakage failure of conformally coated electronic assemblies. , 2008, , .		4
12	Deformation Property Measurement for Single Anisotropic Conductive Adhesive Particles. , 2006, , .		3
13	Mechanical and Electrical Characterisation of Individual ACA Conductor Particles. , 2006, , .		3
14	Materials and Processes Issues in Fine Pitch Eutectic Solder Flip Chip Interconnection. IEEE Transactions on Components and Packaging Technologies, 2006, 29, 869-876.	1.3	2
15	Failure Mechanisms of Dummy IGBT Assemblies Constructed using Liquid In-Sn/Nb System. , 2007, , .		2
16	Characterisation of metal coated polymer balls for BGA and CSP applications. , 2009, , .		2
17	Thermo-mechanical damage accumulation during power cycling of lead-free surface mount solder joints. , 2008, , .		1
18	3D Study of Thermal Stresses in Lead-Free Surface Mount Devices. Journal of Thermal Stresses, 2008, 31, 1039-1055.	2.0	1

#	ARTICLE	IF	CITATIONS
19	Process and performance modelling for individual ACA conductor particles. , 2014, , .		1
20	Non-destructive defect detection for MEMS devices using transient thermography. , 2016, , .		1
21	The effect of droplet ejection frequency on inkjet-etched micro via holes. , 2010, , .		0
22	Characterisation of thermocompression bonds formed using metal coated polymer core particles for fine pitch interconnections. , 2016, , .		0
23	Observations on the implementation of LEDs for general lighting. , 2016, , .		0
24	Magnetic deposition of Ni/Au coated polymer core particles for flip-chip interconnection. , 2014, , .		0